

NUMBER 316516

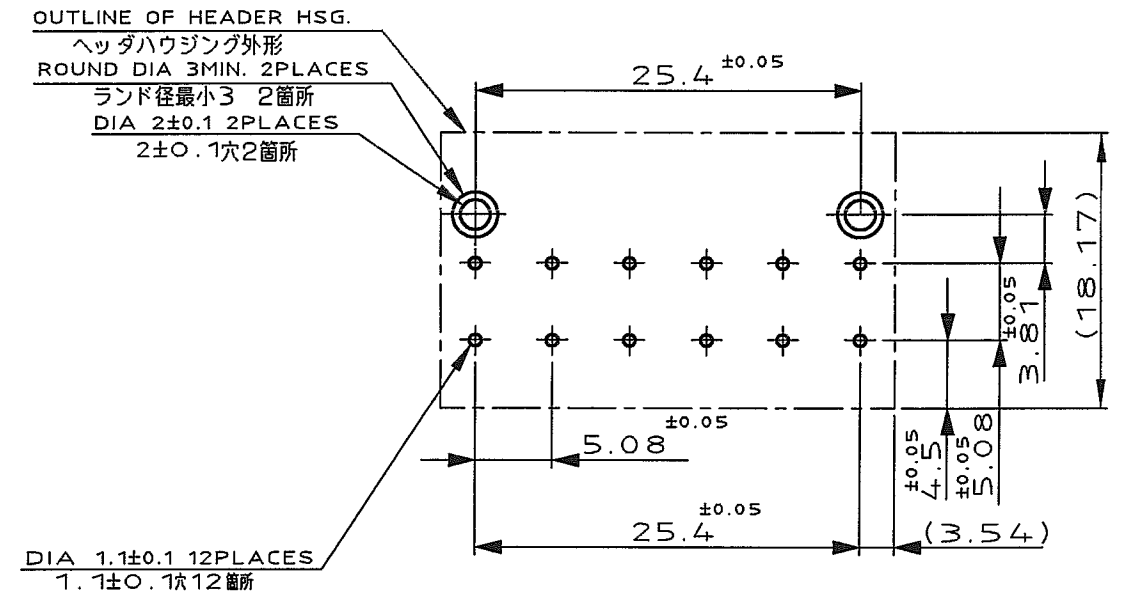
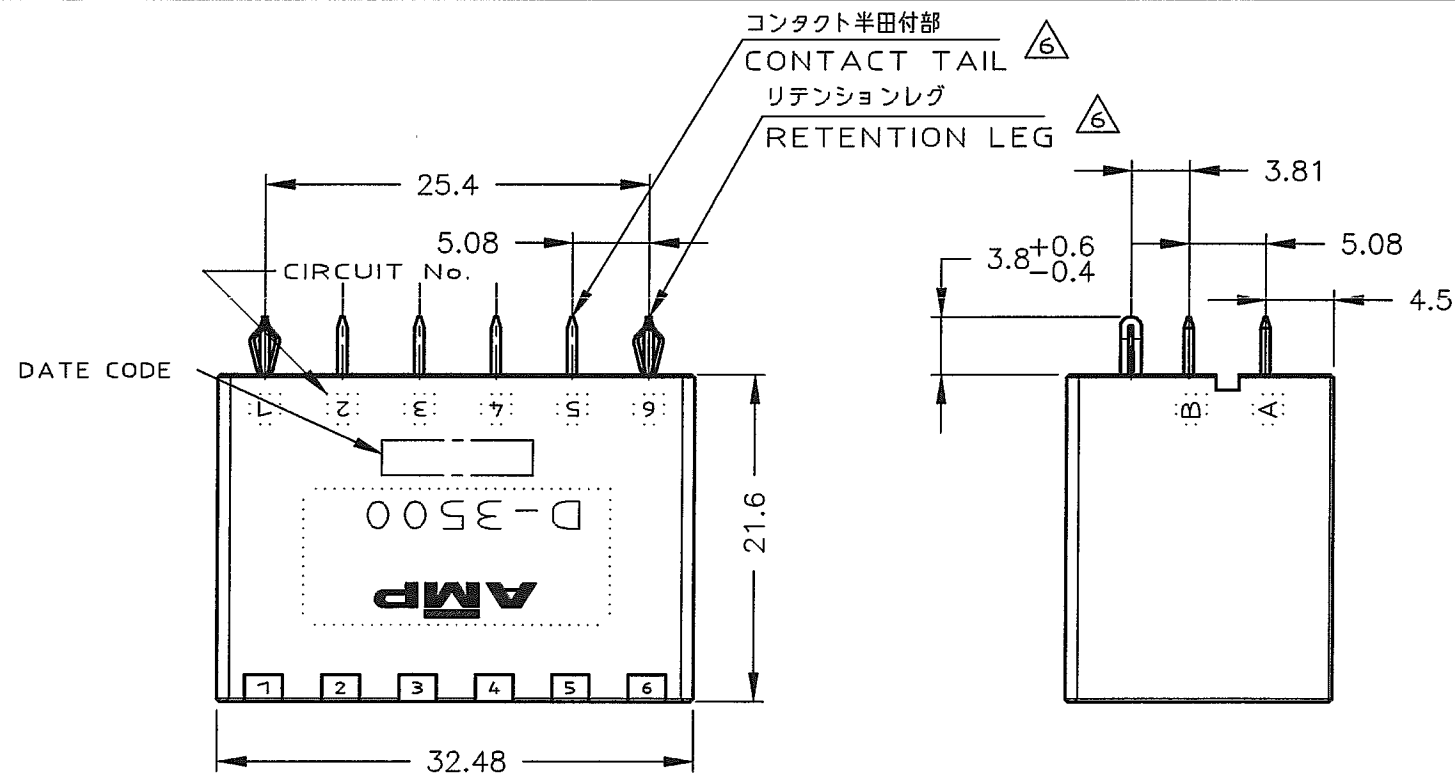
METRIC

PROJ NO.395-623

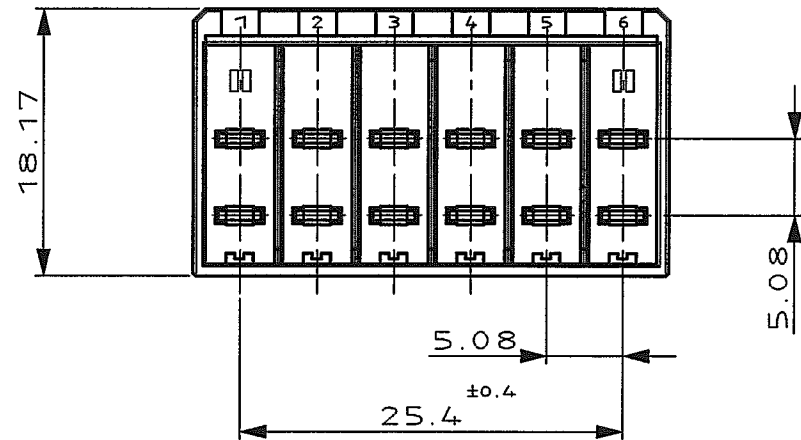
PRINT DIST 単位: 概 DIMENSIONS IN MM. DO NOT SCALE PRINT

PRINT DIST

AMP-J REV.10/83



推奨基板取付け寸法 (非累積公差)
 RECOMEND PC BOARD HOLE (NOT ACCUMULATE TOLERANCE)
 PC BOARD THICKNESS; 1.6 ± 0.1
 基板厚; 1.6 ± 0.1



NOTES

- MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, UL94V-0
 CONTACT: COPPER ALLOY
 RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38 μm PdNi & Au PLATING OVER NICKEL
- FINISH (CONTACT AREA): 0.76 μm PdNi & Au PLATING OVER NICKEL
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

△6	△4		-5
△6	△3		-3
△6	△2	316516-2	
FINISH		型番 PART NUMBER	

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適合電線範囲(WIRE RANGE)				線径外径(INSULATION DIA.)		名称(NAME)	
mm ² (AWG -)				mm ^φ		DYNAMIC(D-3500) 12 POS. V HDR. ASS'Y	
C	REVISED PER ECR-25-250788	F.Z.R.B.	16JAN 2025	材料(MATERIAL) (SEE NOTE) 注記参照	社上(FINISH) (SEE NOTE) 注記参照	一般公差 (GENERAL TOLERANCE)	LOC
B	REVISED (FJD0-0039-03)	T.S.	17/03	DR. 24 OCT 95 N.MATSUBARA	DE. 24 OCT 95 N.MATSUBARA	10mm以下: ±0.35 10mm超 3mm以下: ±0.4 30mm超 100mm以下: ±0.45 角 度: ±3'	A3 J
A	REVISED (FJD0-0114-03)	T.S.	25.APR '03	CHK. 24 OCT 95 Y.ISHIKAWA	APP. 24 OCT 95 S.MANABE	10mm以下: ±0.35 10mm超 3mm以下: ±0.4 30mm超 100mm以下: ±0.45 角 度: ±3'	番号(No.) C-316516
O	RELEASED FJ00-3261-95	NM	10/24 '95				REV. C
LTR	変更 (REVISION RECORD)	DR	CHK DATE				SHEET 1 OF 1